

MATERIAL DATA SHEET

Material #	CDBUR & CDBU series (0603) (Halogen Free)	
Product Line	SOD-523F	
Date	2011/8/25	
Rev.	F	

COMPONENT DETAILS

No.	Construction element	Material group	Material weight (mg)	Material	CAS if applicable	Average mass (%)	Sum(%)	Traces
1	FR-4 Board	Substrate/ Terminal	1.357	Copper	7440-50-8	29.34%	41.45	
				Nickel	7440-02-0	4.762%		
				Gold	7440-57-5	0.155%		
				Continuous Filament Fiber Glass	65997-17-3	65.74%		
2	Wafer	Diode	0.029	Silicon	7440-21-3	92.00%	0.89	
				Aluminum	7429-90-5	1.30%		
				Titanium	7440-32-6	0.20%		
				Gold	7440-57-5	6.50%		
3	Al wire	Conductor	0.001	Aluminum	7429-90-5	99.00%	0.03	
				Silicon	7440-21-3	<1%		
4	Silver paste	Welding	0.006	Modified Epoxy Resin	29690-82-2	5~25%	0.18	
				Silver	7440-22-4	76~85%		
				Imidazole	827-43-0	1~4%		
				Amide	461-58-5	1~4%		
5	Molding Compound	Outer	1.881	Silica	60676-86-0	70~90%	57.45	
				Epoxy Resin	Trade Secret	6~16%		
				Phenolic Resin	Trade Secret	5~15%		
				Carbon Black	1333-86-4	0.1~1%		
		Total weight	3.274					